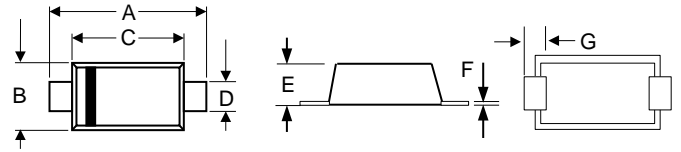


### Features

- \* For surface mounted application
- \* Low Profile Package
- \* Glass Passivated Chip Junction
- \* High Temp Soldering: 260°C for 10seconds at Terminals
- \* Superfast Recovery Times



RoHS  
COMPLIANT



SMBF				
DIM.	INCHES		MM	
	MIN	MAX	MIN	MAX
A	0.201	0.217	5.10	5.50
B	0.138	0.146	3.5	3.7
C	0.165	0.173	4.2	4.4
D	0.075	0.087	1.90	2.20
E	0.043	0.051	1.10	1.30
F	0.007	0.010	0.18	0.26
G	0.031	0.047	0.80	1.20

### Mechanical Data

- \* Case: SMBF Molded plastic
- \* Terminals: Solderable per MIL-STD-750, Method 2026
- \* Polarity: Indicated by cathode band

### Maximum Ratings and Electrical Characteristics (T<sub>A</sub>=25°C unless otherwise noted)

Type Number	Symbols	ES3ABF	ES3BBF	ES3CBF	ES3DBF	ES3GBF	ES3JBF	Unit
Maximum Repetitive Peak Reverse Voltage	V <sub>RRM</sub>	50	100	150	200	400	600	V
Maximum RMS Voltage	V <sub>RMS</sub>	35	70	105	140	280	420	V
Maximum D.C Blocking Voltage	V <sub>DC</sub>	50	100	150	200	400	600	V
Maximum Average Forward Rectified Current	I <sub>F(AV)</sub>	3						A
Peak Forward Surge Current, 8.3ms single half sine-wave	I <sub>FSM</sub>	100						A
Maximum Instantaneous Forward Voltage at 3.0A	V <sub>F</sub>	1.0				1.25	1.7	V
Maximum D.C Reverse Current @ T <sub>J</sub> =25°C at Rated D.C Blocking Voltage @ T <sub>J</sub> =125°C	I <sub>R</sub>	5 100						μA
Maximum Reverse Recovery Time (Note1)	T <sub>rr</sub>	35						nS
Typical Junction Capacitance(Note2)	C <sub>J</sub>	35						pF
Typical thermal resistance (Note3)	R <sub>θJA</sub> R <sub>θJC</sub>	45 15						°C/W
Operating and Storage Temperature Range	T <sub>J</sub> / T <sub>STG</sub>	-55 to +150						°C

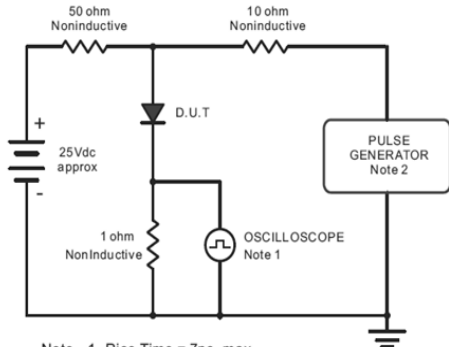
Note 1: Reverse Recovery Test Conditions: I<sub>F</sub>=0.5A, I<sub>R</sub>=1.0A, I<sub>RR</sub>=0.25A

Note 2: Measured at 1 MHz and Applied Reverse Voltage of 4.0V D.C.

Note 3: P.C.B. mounted with 2.0" X 2.0" (5 X 5 cm) copper pad areas.

### Ratings and Characteristic Curves

Fig.1 Reverse Recovery Time Characteristic And Test Circuit Diagram



Note: 1. Rise Time = 7ns, max.  
 Input Impedance = 1 megohm, 22pF.  
 2. Rise Time = 10ns, max.  
 Source Impedance = 50 ohms.

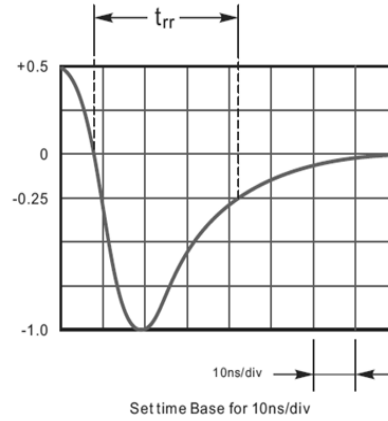


Fig.2 Maximum Average Forward Current Rating

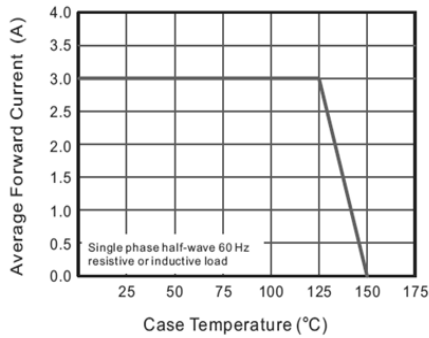


Fig.3 Typical Reverse Characteristics

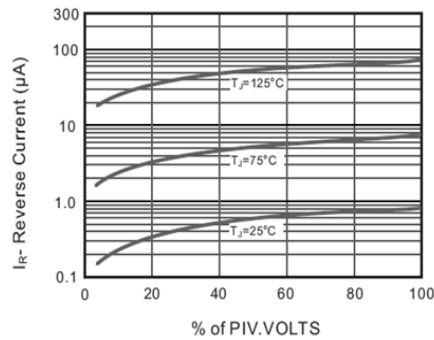


Fig.4 Typical Forward Characteristics

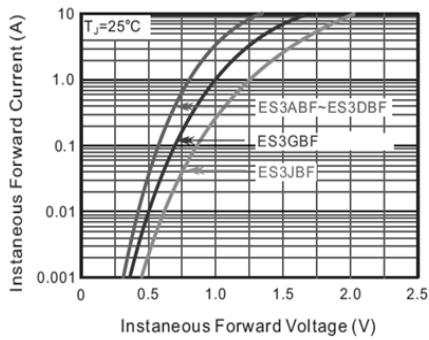


Fig.5 Typical Junction Capacitance

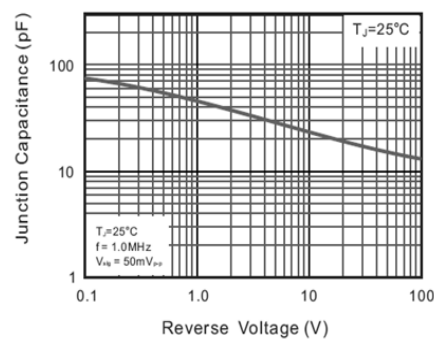
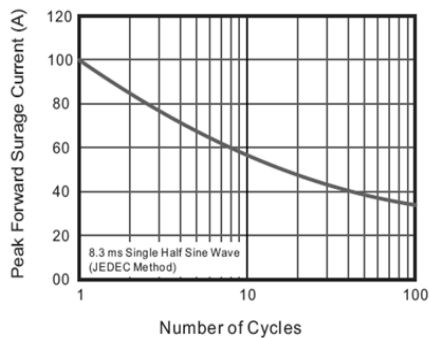


Fig.6 Maximum Non-Repetitive Peak Forward Surge Current





# ES3ABF THRU ES3JBF

3.0 Amp. Surface Mount Glass Passivated Super Fast Rectifiers

## Ordering Information

Part No.	Package	Packing Code	Packing
ES3ABF THRU ES3JBF	SMBF	R50	5000pcs/Reel

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